

PRIORITY STATEMENT

This application is a Divisional of U. S. Patent Application Serial No. 09/811,844 filed on
March 19, 2001.

In The Abstract

Please replace the Abstract with the following:

The invention provides for a method of manufacturing a stacked power chip resistor. The method includes adhering a first chip resistor to a second chip resistor with a glass encapsulant, connecting a first terminal of the first chip resistor to a first terminal of the second chip resistor with the first metal barrier, and connecting a second terminal on the first chip resistor to a second terminal of the second chip resistor with a second metal barrier.

In the Claims

Please cancel claims 1-25 without prejudice.

Please amend claim 26 as follows:

26. (Amended)

A method of manufacturing a stacked power chip resistor comprising:
adhering a first chip resistor to a second chip resistor with a glass encapsulant;
connecting a first terminal of the first chip resistor to a first terminal of the second chip resistor with a first metal barrier;
connecting a second terminal of the first chip resistor to a second terminal of the second chip resistor with a second metal barrier.

Kindly enter the following new claims 29-32: